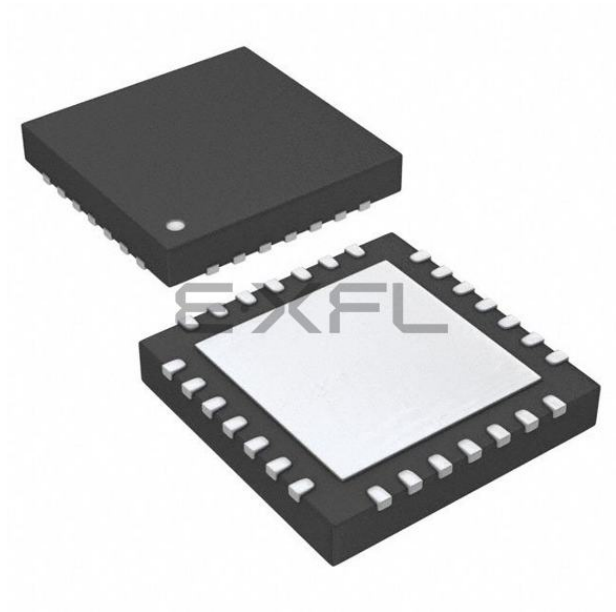

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf2520-i-ml

TABLE 1-3: PIC18F4420/4520 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTE is a bidirectional I/O port.
RE0/$\overline{RD}$/AN5	8	25	25			
RE0				I/O	ST	Digital I/O.
$\overline{RD}$				I	TTL	Read control for Parallel Slave Port (see also $\overline{WR}$ and $\overline{CS}$ pins).
AN5				I	Analog	Analog input 5.
RE1/$\overline{WR}$/AN6	9	26	26			
RE1				I/O	ST	Digital I/O.
$\overline{WR}$				I	TTL	Write control for Parallel Slave Port (see $\overline{CS}$ and $\overline{RD}$ pins).
AN6				I	Analog	Analog input 6.
RE2/$\overline{CS}$/AN7	10	27	27			
RE2				I/O	ST	Digital I/O.
$\overline{CS}$				I	TTL	Chip Select control for Parallel Slave Port (see related $\overline{RD}$ and $\overline{WR}$).
AN7				I	Analog	Analog input 7.
RE3	—	—	—	—	—	See $\overline{MCLR}$/VPP/RE3 pin.
VSS	12, 31	6, 30, 31	6, 29	P	—	Ground reference for logic and I/O pins.
VDD	11, 32	7, 8, 28, 29	7, 28	P	—	Positive supply for logic and I/O pins.
NC	—	13	12, 13, 33, 34	—	—	No Connect.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

4.2 Master Clear ($\overline{MCLR}$)

The $\overline{MCLR}$ pin provides a method for triggering an external Reset of the device. A Reset is generated by holding the pin low. These devices have a noise filter in the $\overline{MCLR}$ Reset path which detects and ignores small pulses.

The $\overline{MCLR}$ pin is not driven low by any internal Resets, including the WDT.

In PIC18F2420/2520/4420/4520 devices, the $\overline{MCLR}$ input can be disabled with the MCLRE Configuration bit. When $\overline{MCLR}$ is disabled, the pin becomes a digital input. See **Section 10.5 "PORTE, TRISE and LATE Registers"** for more information.

4.3 Power-on Reset (POR)

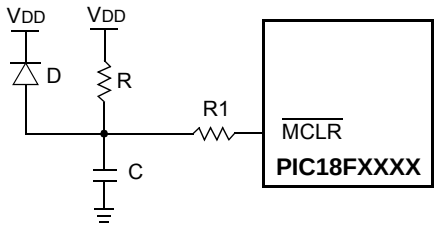
A Power-on Reset pulse is generated on-chip whenever VDD rises above a certain threshold. This allows the device to start in the initialized state when VDD is adequate for operation.

To take advantage of the POR circuitry, tie the $\overline{MCLR}$ pin through a resistor (1 kΩ to 10 kΩ) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified (parameter D004). For a slow rise time, see Figure 4-2.

When the device starts normal operation (i.e., exits the Reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

POR events are captured by the $\overline{POR}$ bit (RCON<1>). The state of the bit is set to '0' whenever a POR occurs; it does not change for any other Reset event. $\overline{POR}$ is not reset to '1' by any hardware event. To capture multiple events, the user manually resets the bit to '1' in software following any POR.

FIGURE 4-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 ≥ 1 kΩ will limit any current flowing into $\overline{MCLR}$ from external capacitor C, in the event of $\overline{MCLR}$/VPP pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

4.6 Reset State of Registers

Most registers are unaffected by a Reset. Their status is unknown on POR and unchanged by all other Resets. The other registers are forced to a “Reset state” depending on the type of Reset that occurred.

Most registers are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. Status bits from the RCON register, $\overline{RI}$, $\overline{TO}$, $\overline{PD}$, $\overline{POR}$ and $\overline{BOR}$, are set or cleared differently in different Reset situations, as indicated in Table 4-3. These bits are used in software to determine the nature of the Reset.

Table 4-4 describes the Reset states for all of the Special Function Registers. These are categorized by Power-on and Brown-out Resets, Master Clear and WDT Resets and WDT wake-ups.

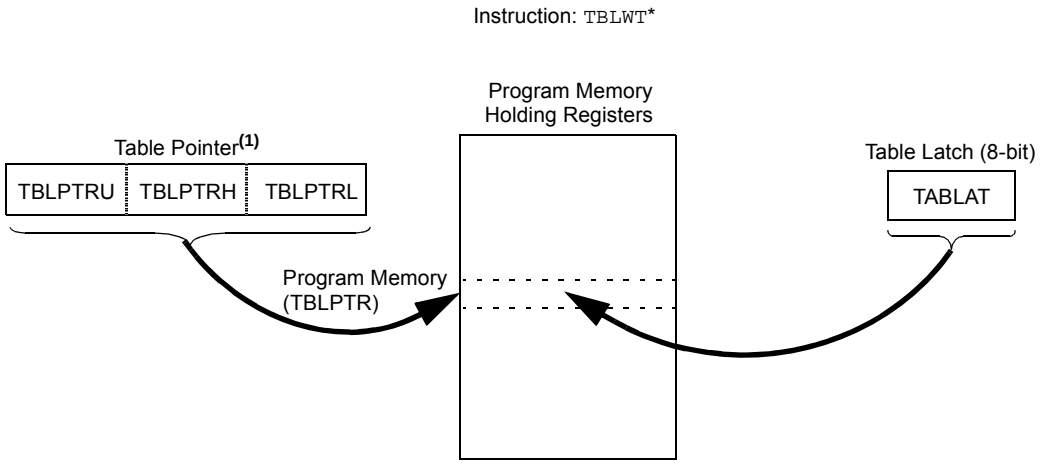
TABLE 4-3: STATUS BITS, THEIR SIGNIFICANCE AND THE INITIALIZATION CONDITION FOR RCON REGISTER

Condition	Program Counter	RCON Register					STKPTR Register	
		$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	STKFUL	STKUNF
Power-on Reset	0000h	1	1	1	0	0	0	0
RESET Instruction	0000h	0	u	u	u	u	u	u
Brown-out Reset	0000h	1	1	1	u	0	u	u
$\overline{MCLR}$ Reset during Power-Managed Run Modes	0000h	u	1	u	u	u	u	u
$\overline{MCLR}$ Reset during Power-Managed Idle Modes and Sleep Mode	0000h	u	1	0	u	u	u	u
WDT Time-out during Full Power or Power-Managed Run Mode	0000h	u	0	u	u	u	u	u
$\overline{MCLR}$ Reset during Full-Power Execution	0000h	u	u	u	u	u	u	u
Stack Full Reset (STVREN = 1)	0000h	u	u	u	u	u	1	u
Stack Underflow Reset (STVREN = 1)	0000h	u	u	u	u	u	u	1
Stack Underflow Error (not an actual Reset, STVREN = 0)	0000h	u	u	u	u	u	u	1
WDT Time-out during Power-Managed Idle or Sleep Modes	PC + 2	u	0	0	u	u	u	u
Interrupt Exit from Power-Managed Modes	PC + 2(1)	u	u	0	u	u	u	u

Legend: u = unchanged

Note 1: When the wake-up is due to an interrupt and the GIEH or GIEL bits are set, the PC is loaded with the interrupt vector (008h or 0018h).

FIGURE 6-2: TABLE WRITE OPERATION



Note1: The Table Pointer actually points to one of 32 holding registers, the address of which is determined by TBLPTRL<4:0>. The process for physically writing data to the program memory array is discussed in **Section 6.5 "Writing to Flash Program Memory"**.

6.2 Control Registers

Several control registers are used in conjunction with the TBLRD and TBLWT instructions. These include the:

- EECON1 register
- EECON2 register
- TABLAT register
- TBLPTR registers

6.2.1 EECON1 AND EECON2 REGISTERS

The EECON1 register (Register 6-1) is the control register for memory accesses. The EECON2 register is not a physical register; it is used exclusively in the memory write and erase sequences. Reading EECON2 will read all '0's.

The EEPGD control bit determines if the access will be a program or data EEPROM memory access. When clear, any subsequent operations will operate on the data EEPROM memory. When set, any subsequent operations will operate on the program memory.

The CFGS control bit determines if the access will be to the Configuration/Calibration registers or to program memory/data EEPROM memory. When set, subsequent operations will operate on Configuration registers regardless of EEPGD (see **Section 23.0 "Special Features of the CPU"**). When clear, memory selection access is determined by EEPGD.

The FREE bit, when set, will allow a program memory erase operation. When FREE is set, the erase operation is initiated on the next WR command. When FREE is clear, only writes are enabled.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set in hardware when the WR bit is set and cleared when the internal programming timer expires and the write operation is complete.

Note:	During normal operation, the WRERR is read as '1'. This can indicate that a write operation was prematurely terminated by a Reset, or a write operation was attempted improperly.

The WR control bit initiates write operations. The bit cannot be cleared, only set, in software; it is cleared in hardware at the completion of the write operation.

Note:	The EEIF interrupt flag bit (PIR2<4>) is set when the write is complete. It must be cleared in software.

9.3 PIE Registers

The PIE registers contain the individual enable bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are two Peripheral Interrupt Enable registers (PIE1 and PIE2). When IPEN = 0, the PEIE bit must be set to enable any of these peripheral interrupts.

REGISTER 9-6: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **PSPIE:** Parallel Slave Port Read/Write Interrupt Enable bit(1)
- 1 = Enables the PSP read/write interrupt
- 0 = Disables the PSP read/write interrupt

bit 6 **ADIE:** A/D Converter Interrupt Enable bit
- 1 = Enables the A/D interrupt
- 0 = Disables the A/D interrupt

bit 5 **RCIE:** EUSART Receive Interrupt Enable bit
- 1 = Enables the EUSART receive interrupt
- 0 = Disables the EUSART receive interrupt

bit 4 **TXIE:** EUSART Transmit Interrupt Enable bit
- 1 = Enables the EUSART transmit interrupt
- 0 = Disables the EUSART transmit interrupt

bit 3 **SSPIE:** Master Synchronous Serial Port Interrupt Enable bit
- 1 = Enables the MSSP interrupt
- 0 = Disables the MSSP interrupt

bit 2 **CCP1IE:** CCP1 Interrupt Enable bit
- 1 = Enables the CCP1 interrupt
- 0 = Disables the CCP1 interrupt

bit 1 **TMR2IE:** TMR2 to PR2 Match Interrupt Enable bit
- 1 = Enables the TMR2 to PR2 match interrupt
- 0 = Disables the TMR2 to PR2 match interrupt

bit 0 **TMR1IE:** TMR1 Overflow Interrupt Enable bit
- 1 = Enables the TMR1 overflow interrupt
- 0 = Disables the TMR1 overflow interrupt

Note 1: This bit is unimplemented on 28-pin devices and will read as '0'.

TABLE 10-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
PORTA	RA7(1)	RA6(1)	RA5	RA4	RA3	RA2	RA1	RA0	52
LATA	LATA7(1)	LATA6(1)	PORTA Data Latch Register (Read and Write to Data Latch)						52
TRISA	TRISA7(1)	TRISA6(1)	PORTA Data Direction Register						52
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	51
CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	51
CVRCON	CVREN	CVROE	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0	51

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTA.

Note 1: RA<7:6> and their associated latch and data direction bits are enabled as I/O pins based on oscillator configuration; otherwise, they are read as '0'.

17.4.17.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDA when SCL goes from low level to high level.

b) SCL goes low before SDA is asserted low, indicating that another master is attempting to transmit a data '1'.

When the user deasserts SDA and the pin is allowed to float high, the BRG is loaded with SSPADD<6:0> and counts down to 0. The SCL pin is then deasserted and when sampled high, the SDA pin is sampled.

If SDA is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', Figure 17-29). If SDA is sampled high, the BRG is reloaded and begins counting. If SDA goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDA at exactly the same time.

If SCL goes from high-to-low before the BRG times out and SDA has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition, see Figure 17-30.

If, at the end of the BRG time-out, both SCL and SDA are still high, the SDA pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCL pin, the SCL pin is driven low and the Repeated Start condition is complete.

FIGURE 17-29: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

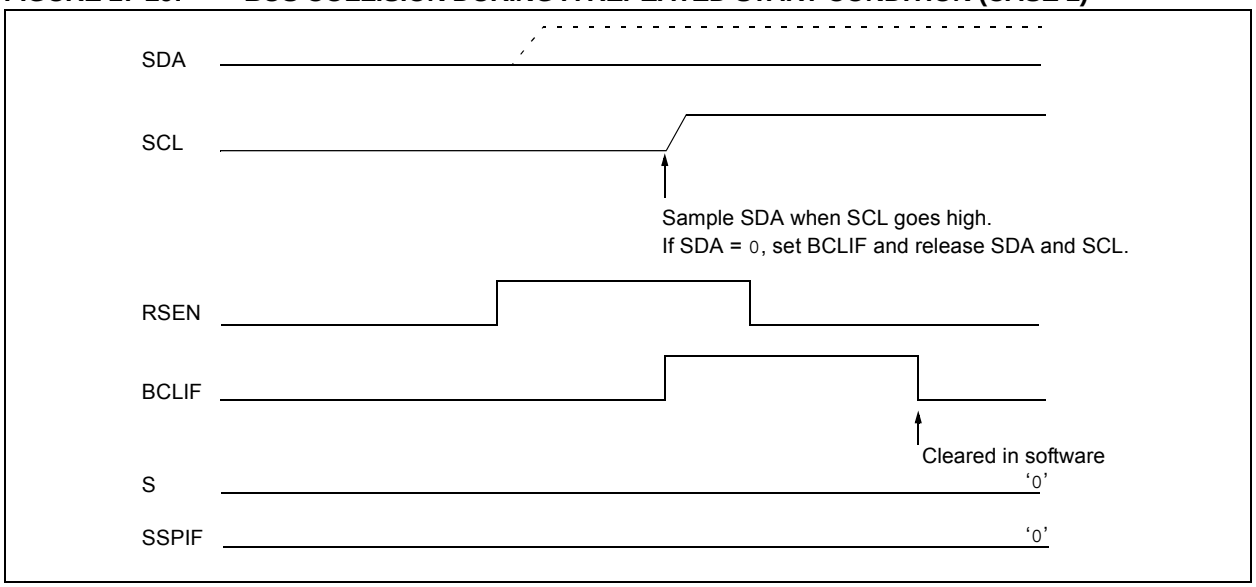
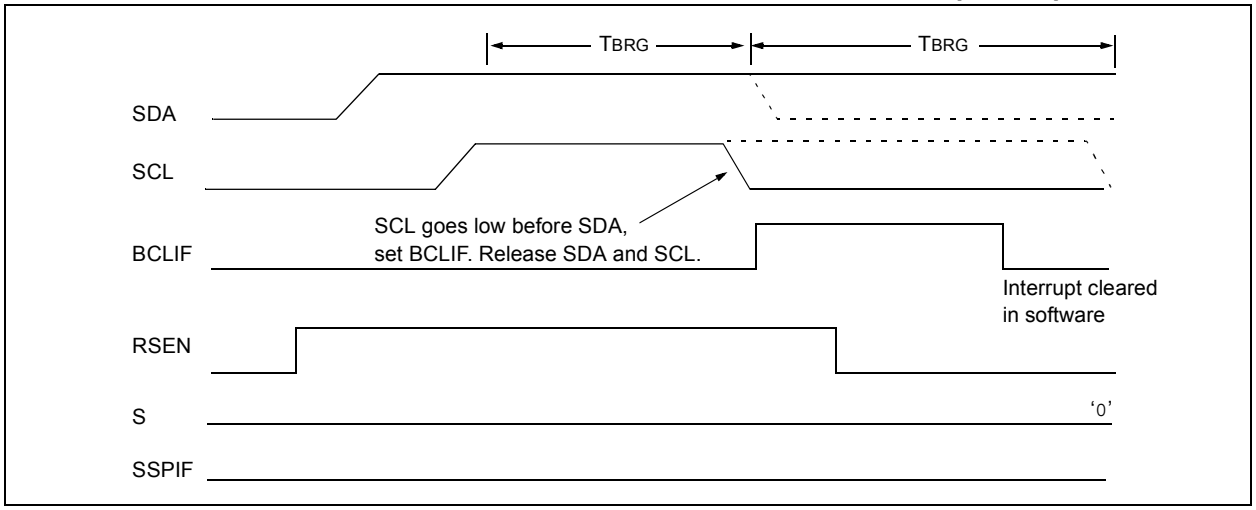


FIGURE 17-30: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



18.1 Baud Rate Generator (BRG)

The BRG is a dedicated, 8-bit or 16-bit generator that supports both the Asynchronous and Synchronous modes of the EUSART. By default, the BRG operates in 8-bit mode; setting the BRG16 bit (BAUDCON<3>) selects 16-bit mode.

The SPBRGH:SPBRG register pair controls the period of a free-running timer. In Asynchronous mode, bits, BRGH (TXSTA<2>) and BRG16 (BAUDCON<3>), also control the baud rate. In Synchronous mode, BRGH is ignored. Table 18-1 shows the formula for computation of the baud rate for different EUSART modes which only apply in Master mode (internally generated clock).

Given the desired baud rate and FOSC, the nearest integer value for the SPBRGH:SPBRG registers can be calculated using the formulas in Table 18-1. From this, the error in baud rate can be determined. An example calculation is shown in Example 18-1. Typical baud rates and error values for the various Asynchronous modes are shown in Table 18-2. It may be advantageous to use the high baud rate (BRGH = 1) or the 16-bit BRG to reduce the baud rate error, or achieve a slow baud rate for a fast oscillator frequency.

Writing a new value to the SPBRGH:SPBRG registers causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

18.1.1 OPERATION IN POWER-MANAGED MODES

The device clock is used to generate the desired baud rate. When one of the power-managed modes is entered, the new clock source may be operating at a different frequency. This may require an adjustment to the value in the SPBRG register pair.

18.1.2 SAMPLING

The data on the RX pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

TABLE 18-1: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-Bit/Asynchronous	FOSC/[64 (n + 1)]
0	0	1	8-Bit/Asynchronous	FOSC/[16 (n + 1)]
0	1	0	16-Bit/Asynchronous	
0	1	1	16-Bit/Asynchronous	FOSC/[4 (n + 1)]
1	0	x	8-Bit/Synchronous	
1	1	x	16-Bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH:SPBRG register pair

20.0 COMPARATOR MODULE

The analog comparator module contains two comparators that can be configured in a variety of ways. The inputs can be selected from the analog inputs multiplexed with pins, RA0 through RA5, as well as the on-chip voltage reference (see **Section 21.0 "Comparator Voltage Reference Module"**). The digital outputs (normal or inverted) are available at the pin level and can also be read through the control register.

The CMCON register (Register 20-1) selects the comparator input and output configuration. Block diagrams of the various comparator configurations are shown in Figure 20-1.

REGISTER 20-1: CMCON: COMPARATOR CONTROL REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **C2OUT**: Comparator 2 Output bit
When C2INV = 0:
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-
When C2INV = 1:
1 = C2 VIN+ < C2 VIN-
0 = C2 VIN+ > C2 VIN-

bit 6 **C1OUT**: Comparator 1 Output bit
When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-
When C1INV = 1:
1 = C1 VIN+ < C1 VIN-
0 = C1 VIN+ > C1 VIN-

bit 5 **C2INV**: Comparator 2 Output Inversion bit
1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV**: Comparator 1 Output Inversion bit
1 = C1 output inverted
0 = C1 output not inverted

bit 3 **CIS**: Comparator Input Switch bit
When CM<2:0> = 110:
1 = C1 VIN- connects to RA3/AN3/VREF+
C2 VIN- connects to RA2/AN2/VREF-/CVREF
0 = C1 VIN- connects to RA0/AN0
C2 VIN- connects to RA1/AN1

bit 2-0 **CM<2:0>**: Comparator Mode bits
Figure 20-1 shows the Comparator modes and the CM<2:0> bit settings.

NOTES:

BRA **Unconditional Branch**

Syntax: BRA n

Operands: -1024 ≤ n ≤ 1023

Operation: (PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1101	0nnn	nnnn	nnnn

Description: Add the 2's complement number, '2n', to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is a two-cycle instruction.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

Example: HERE BRA Jump

Before Instruction
PC = address (HERE)
After Instruction
PC = address (Jump)

BSF **Bit Set f**

Syntax: BSF f, b {,a}

Operands: 0 ≤ f ≤ 255
0 ≤ b ≤ 7
a ∈ [0,1]

Operation: 1 → f<b>

Status Affected: None

Encoding:

1000	bbba	ffff	ffff

Description: Bit 'b' in register 'f' is set.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: BSF FLAG_REG, 7, 1

Before Instruction
FLAG_REG = 0Ah
After Instruction
FLAG_REG = 8Ah

INCFSZ **Increment f, Skip if 0**

Syntax: INCFSZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest,
skip if result = 0

Status Affected: None

Encoding:

0011	11da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If the result is '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a two-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    INCFSZ   CNT, 1, 0
NZERO   :
ZERO    :
```

Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT + 1
If CNT = 0;
PC = Address (ZERO)
If CNT ≠ 0;
PC = Address (NZERO)

INFSNZ **Increment f, Skip if Not 0**

Syntax: INFSNZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest,
skip if result ≠ 0

Status Affected: None

Encoding:

0100	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If the result is not '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a two-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    INFSNZ  REG, 1, 0
ZERO
NZERO
```

Before Instruction
PC = Address (HERE)
After Instruction
REG = REG + 1
If REG ≠ 0;
PC = Address (NZERO)
If REG = 0;
PC = Address (ZERO)

MOVFF **Move f to f**

Syntax: MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$
$0 \le f_d \le 4095$

Operation: $(f_s) \rightarrow f_d$

Status Affected: None

Encoding:

1st word (source)	1100	ffff	ffff	$ffff_s$
2nd word (destin.)	1111	ffff	ffff	$ffff_d$

Description: The contents of source register 'f_s' are moved to destination register 'f_d'. Location of source 'f_s' can be anywhere in the 4096-byte data space (000h to FFFh) and location of destination 'f_d' can also be anywhere from 000h to FFFh.
Either source or destination can be W (a useful special situation).
MOVFF is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).
The MOVFF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.

Words: 2

Cycles: 2 (3)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: MOVFF REG1, REG2

Before Instruction
REG1 = 33h
REG2 = 11h
After Instruction
REG1 = 33h
REG2 = 33h

MOVLB **Move Literal to Low Nibble in BSR**

Syntax: MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow$ BSR

Status Affected: None

Encoding:

0000	0001	kkkk	kkkk

Description: The 8-bit literal 'k' is loaded into the Bank Select Register (BSR). The value of BSR<7:4> always remains '0', regardless of the value of k_7:k_4.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR

Example: MOVLB 5

Before Instruction
BSR Register = 02h
After Instruction
BSR Register = 05h

MOVSS **Move Indexed to Indexed**

Syntax: MOVSS [z_s], [z_d]

Operands: $0 \le z_s \le 127$
$0 \le z_d \le 127$

Operation: ((FSR2) + z_s) → ((FSR2) + z_d)

Status Affected: None

Encoding:

1st word (source)	1110	1011	1zzz	$zzzz_s$
2nd word (dest.)	1111	xxxx	xzzz	$zzzz_d$

Description: The contents of the source register are moved to the destination register. The addresses of the source and destination registers are determined by adding the 7-bit literal offsets 'z_s' or 'z_d', respectively, to the value of FSR2. Both registers can be located anywhere in the 4096-byte data memory space (000h to FFFh).
The MOVSS instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.
If the resultant source address points to an indirect addressing register, the value returned will be 00h. If the resultant destination address points to an indirect addressing register, the instruction will execute as a NOP.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Determine source addr	Determine source addr	Read source reg
Decode	Determine dest addr	Determine dest addr	Write to dest reg

Example: MOVSS [05h], [06h]

Before Instruction
FSR2 = 80h
Contents of 85h = 33h
Contents of 86h = 11h
After Instruction
FSR2 = 80h
Contents of 85h = 33h
Contents of 86h = 33h

PUSHL **Store Literal at FSR2, Decrement FSR2**

Syntax: PUSHL k

Operands: $0 \le k \le 255$

Operation: k → (FSR2),
FSR2 – 1 → FSR2

Status Affected: None

Encoding:

1111	1010	kkkk	kkkk

Description: The 8-bit literal 'k' is written to the data memory address specified by FSR2. FSR2 is decremented by 1 after the operation. This instruction allows users to push values onto a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read 'k'	Process data	Write to destination

Example: PUSHL 08h

Before Instruction
FSR2H:FSR2L = 01ECh
Memory (01ECh) = 00h

After Instruction
FSR2H:FSR2L = 01EBh
Memory (01ECh) = 08h

26.2 DC Characteristics: Power-Down and Supply Current PIC18F2420/2520/4420/4520 (Industrial) PIC18LF2420/2520/4420/4520 (Industrial) (Continued)

PIC18LF2420/2520/4420/4520 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F2420/2520/4420/4520 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF2X2X/4X20	250	350	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**PRI_RUN**, EC oscillator)
		260	350	µA	+25°C		
		250	350	µA	+85°C		
	PIC18LF2X2X/4X20	550	650	µA	-40°C	VDD = 3.0V	
		480	640	µA	+25°C		
		460	600	µA	+85°C		
	All devices	1.2	1.5	mA	-40°C	VDD = 5.0V	
		1.1	1.4	mA	+25°C		
		1.0	1.3	mA	+85°C		
	Extended devices only	1.0	3.0	mA	+125°C		
	PIC18LF2X2X/4X20	0.72	1.0	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**PRI_RUN**, EC oscillator)
		0.74	1.0	mA	+25°C		
		0.74	1.0	mA	+85°C		
	PIC18LF2X2X/4X20	1.3	1.8	mA	-40°C	VDD = 3.0V	
		1.3	1.8	mA	+25°C		
		1.3	1.8	mA	+85°C		
	All devices	2.7	4.0	mA	-40°C	VDD = 5.0V	
		2.6	4.0	mA	+25°C		
		2.5	4.0	mA	+85°C		
	Extended devices only	2.6	5.0	mA	+125°C		
	Extended devices only	8.4	13	mA	+125°C	VDD = 4.2V	FOSC = 25 MHz (**PRI_RUN**, EC oscillator)
		11	16	mA	+125°C	VDD = 5.0V	
	All devices	15	20	mA	-40°C	VDD = 4.2V	FOSC = 40 MHz (**PRI_RUN**, EC oscillator)
		15	20	mA	+25°C		
		15	20	mA	+85°C		
	All devices	20	25	mA	-40°C	VDD = 5.0V	
		20	25	mA	+25°C		
		20	25	mA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

26.3 DC Characteristics: PIC18F2420/2520/4420/4520 (Industrial) PIC18LF2420/2520/4420/4520 (Industrial) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**				
D080		I/O Ports	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083		OSC2/CLKO (RC, RCIO, EC, ECIO modes)	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	VOH	**Output High Voltage(3)**				
D090		I/O Ports	VDD – 0.7	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092		OSC2/CLKO (RC, RCIO, EC, ECIO modes)	VDD – 0.7	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
		Capacitive Loading Specs on Output Pins				
D100	COSC2	OSC2 pin	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O pins and OSC2 (in RC mode)	—	50	pF	To meet the AC Timing Specifications
D102	CB	SCL, SDA	—	400	pF	I^2C™ Specification

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

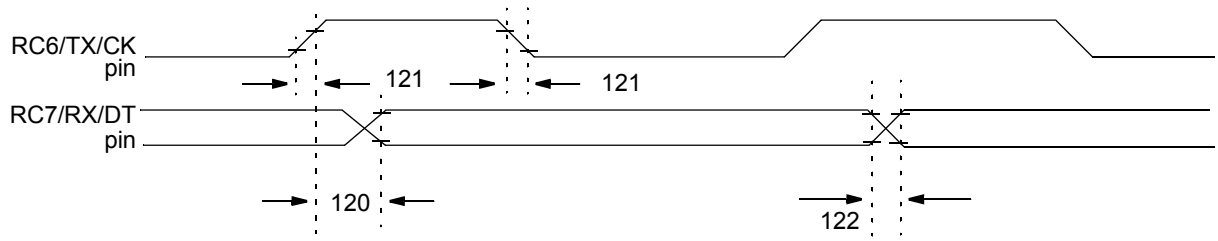
TABLE 26-1: MEMORY PROGRAMMING REQUIREMENTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Data EEPROM Memory					
D120	ED	Byte Endurance	100K	1M	—	E/W	-40°C to +85°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write Cycle Time	—	4	—	ms	
D123	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D124	TREF	Number of Total Erase/Write Cycles before Refresh(1)	1M	10M	—	E/W	-40°C to +85°C
D125	IDDP	Supply Current during Programming	—	10	—	mA	
		Program Flash Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C to +85°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VIE	VDD for Block Erase	3.0	—	5.5	V	Using ICSP™ port, +25°C
D132A	VIW	VDD for Externally Timed Erase or Write	4.5	—	5.5	V	Using ICSP™ port, +25°C
D132B	VPEW	VDD for Self-Timed Write	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D133	TIE	ICSP Block Erase Cycle Time	—	4	—	ms	VDD ≥ 4.5V
D133A	TIW	ICSP Erase or Write Cycle Time (externally timed)	1	—	—	ms	VDD ≥ 4.5V, +25°C
D133A	TIW	Self-Timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	100	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Refer to **Section 7.8 "Using the Data EEPROM"** for a more detailed discussion on data EEPROM endurance.

FIGURE 26-21: EUSART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



Note: Refer to Figure 26-5 for load conditions.

TABLE 26-22: EUSART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock High to Data Out Valid	PIC18**F**XXXX	—	40	ns	
			PIC18**LF**XXXX	—	100	ns	VDD = 2.0V
121	Tckrf	Clock Out Rise Time and Fall Time (Master mode)	PIC18**F**XXXX	—	20	ns	
			PIC18**LF**XXXX	—	50	ns	VDD = 2.0V
122	Tdtrf	Data Out Rise Time and Fall Time	PIC18**F**XXXX	—	20	ns	
			PIC18**LF**XXXX	—	50	ns	VDD = 2.0V

FIGURE 27-11: TYPICAL IDD ACROSS VDD (RC_RUN MODE, +25°C)

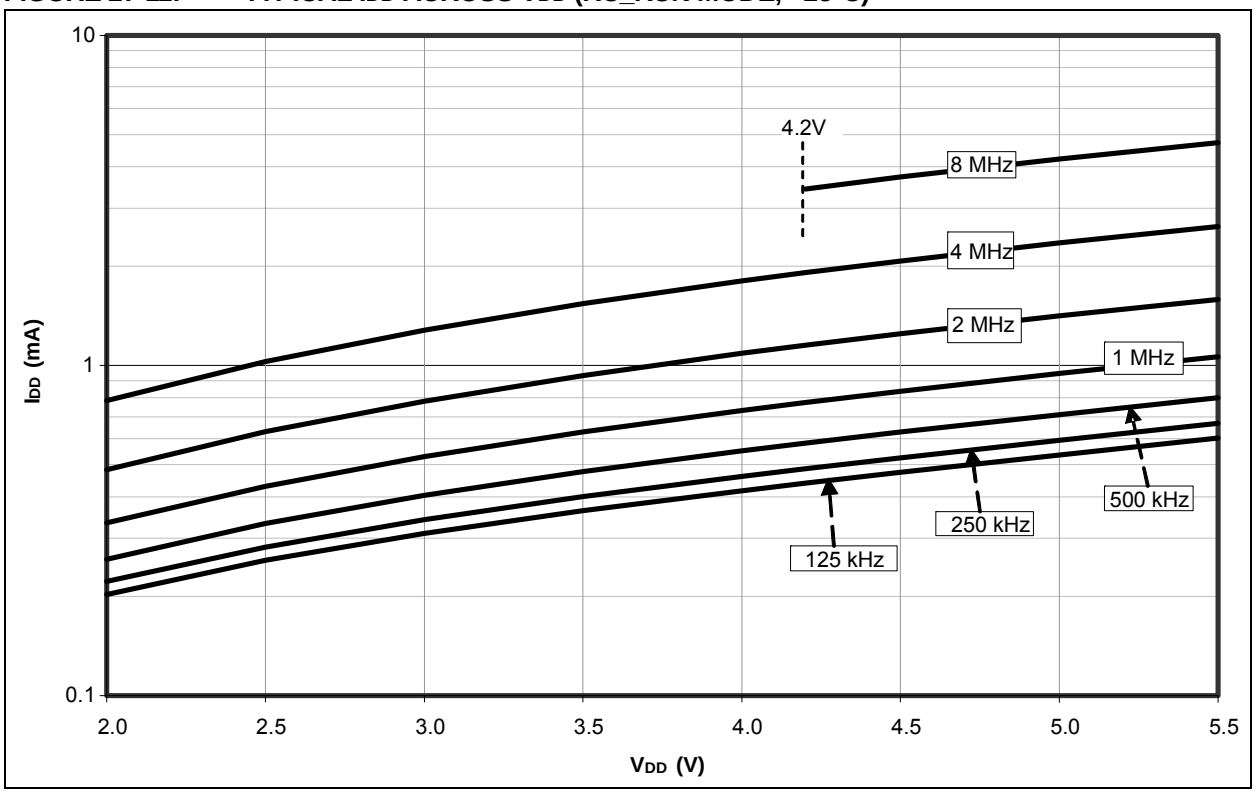


FIGURE 27-12: MAXIMUM IDD ACROSS VDD (RC_RUN MODE, +85°C)

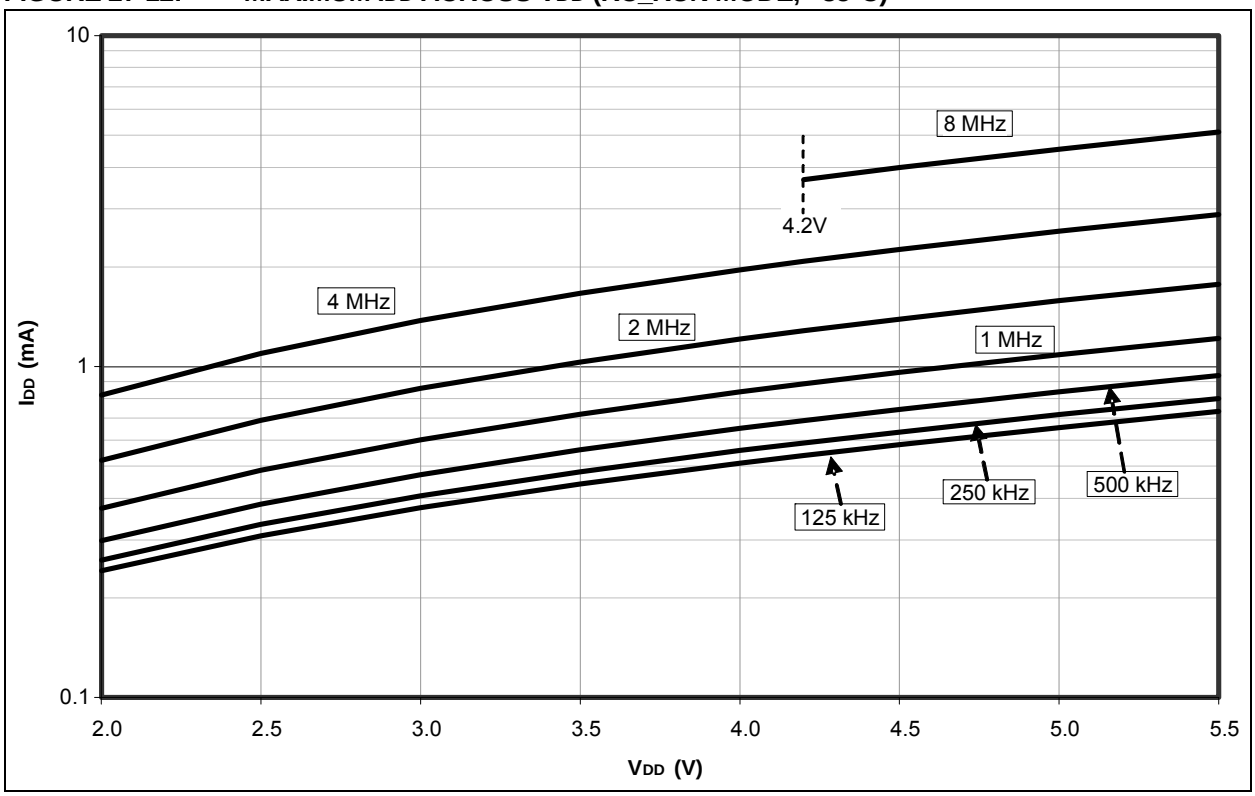


FIGURE 27-35: VOH vs. IOH (VDD = 3.0V, -40°C TO +85°C)

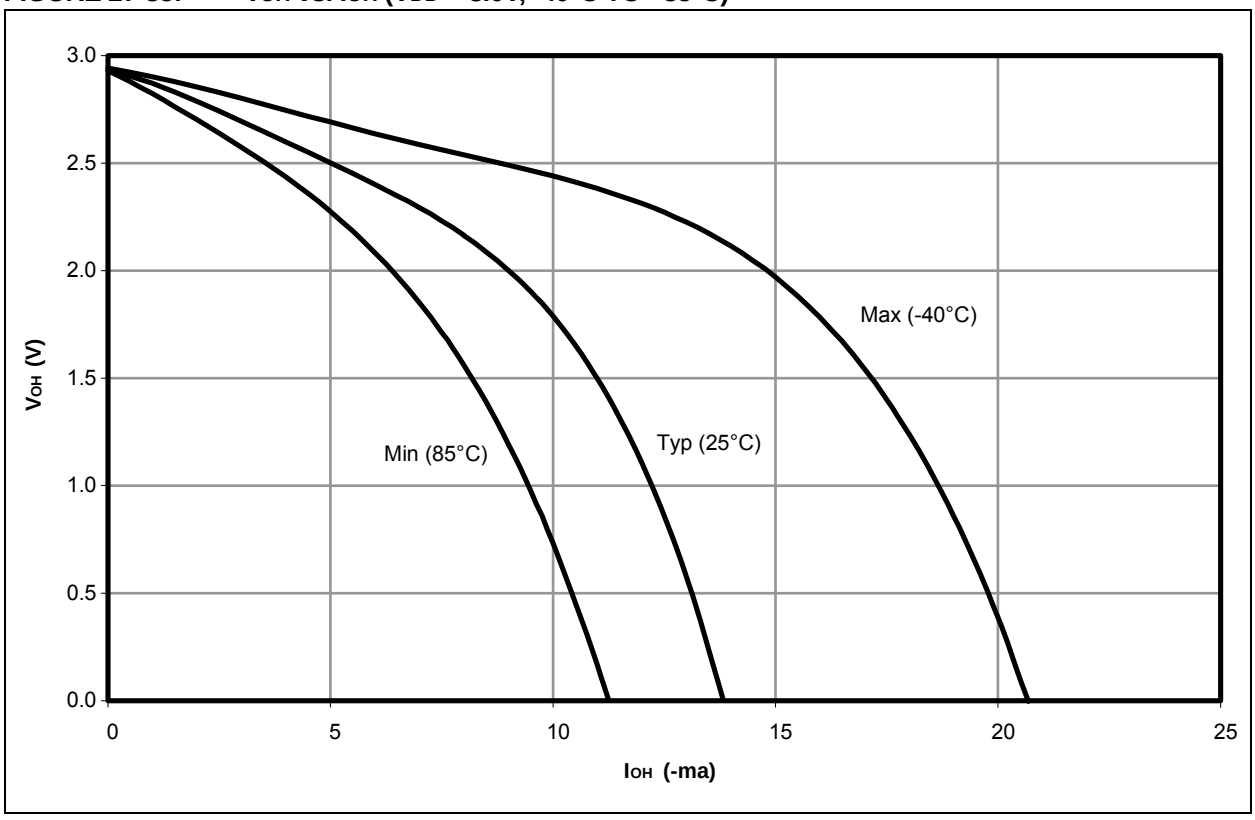


FIGURE 27-36: VOH vs. IOH (VDD = 5.0V, -40°C TO +125°C)